



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-04-27
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMG Material Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
LM2903D	IDO7*0393BC6	A	BO2A	2017-04-27
Amount		UoM	Unit type	ST ECOPACK Grade
80		mg	Each	ECOPACK® 3

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
ating is used or other bulk terminati	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.85x3.9x1.52	8	gull wing	
Comment	Package: SO 08 .15 JEDEC			

QueryList : ROHS directive 2011/65/EU _ July 2011				
Query				Response
1 - Product(s) meets EU RoHS requirement without any exemptions				true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)				false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)				false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions				false
5 - Product(s) is obsolete, no information is available				false
6 - Product(s) is unknown, no information is available				false
Exemption Id.	Description			
QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	IDO7*0393BC6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	0.548	mg	supplier	die	Silicon (Si)	7440-21-3		0.539	mg	983577	6738
				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	7299	50
				supplier	passivation	Silicon Nitride (SiN)	12033-89-5		0.002	mg	3650	25
				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.003	mg	5474	38
Leadframe	Copper & its alloys	28.967	mg	supplier	alloy	Copper (Cu)	7440-50-8		27.900	mg	963165	348750
				supplier	alloy	Iron (Fe)	7439-89-6		0.656	mg	22646	8200
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.040	mg	1381	500
				supplier	alloy	Zinc (Zn)	7440-66-6		0.034	mg	1174	425
				supplier	metallization	Nickel (Ni)	7440-02-0		0.313	mg	10805	3913
				supplier	metallization	Palladium (Pd)	7440-05-3		0.013	mg	449	163
Die attach	Other inorganic materials	0.273	mg	supplier	metallization	Gold (Au)	7440-57-5		0.011	mg	380	138
				supplier	glue or tape (choose)	Silver (Ag)	7440-22-4		0.248	mg	908425	3100
				supplier	glue or tape	acrylate	Proprietary		0.014	mg	51282	175
Bonding wire	Other inorganic materials	0.072	mg	supplier	glue or tape	Methacrylate	Proprietary		0.011	mg	40293	138
				supplier	wire	Copper (Cu)	7440-50-8		0.072	mg	1000000	900
				supplier	mold compound	Epoxy Resin	Proprietary		3.760	mg	74990	47000
encapsulation	Other inorganic materials	50.140	mg	supplier	mold compound	Phenol Resin	Proprietary		2.507	mg	50000	31338
				supplier	mold compound	Silica, vitreous	60676-86-0		43.421	mg	865995	542763
				supplier	mold compound	Carbon black	1333-86-4		0.251	mg	5006	3138
				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.201	mg	4009	2513